

(b) starting the supply of the coolant in the coolant path when the substrate or the placing table changes in state, thereby cooling the placing table together with the substrate; and

(c) unloading the substrate from the placing table after the temperature of the placing table is rendered equal to or lower than the target temperature, and ^{temperature winding} heating the substrate to the target temperature in an atmosphere having a temperature substantially equal to the target temperature.

19. (New) A cooling method according to claim 18, further comprising:

starting the supply of the coolant when the temperature of the placing table changes or a predetermined time passes after the temperature of the placing table changed.

20. (New) A cooling method according to claim 18, further comprising:

starting the supply of the coolant when the substrate is placed on the placing table or when a predetermined time passes after the substrate was placed on the placing table.

21. (New) A cooling method according to claim 18, further comprising:

starting the supply of the coolant when, after the substrate is received by means of a plurality of support pins above the placing table, and the support pins are descended, or when a predetermined time passes after the support pins are descended.

REMARKS

Favorable reconsideration of this application, as presently amended and in light of the following discussion, is respectfully requested.